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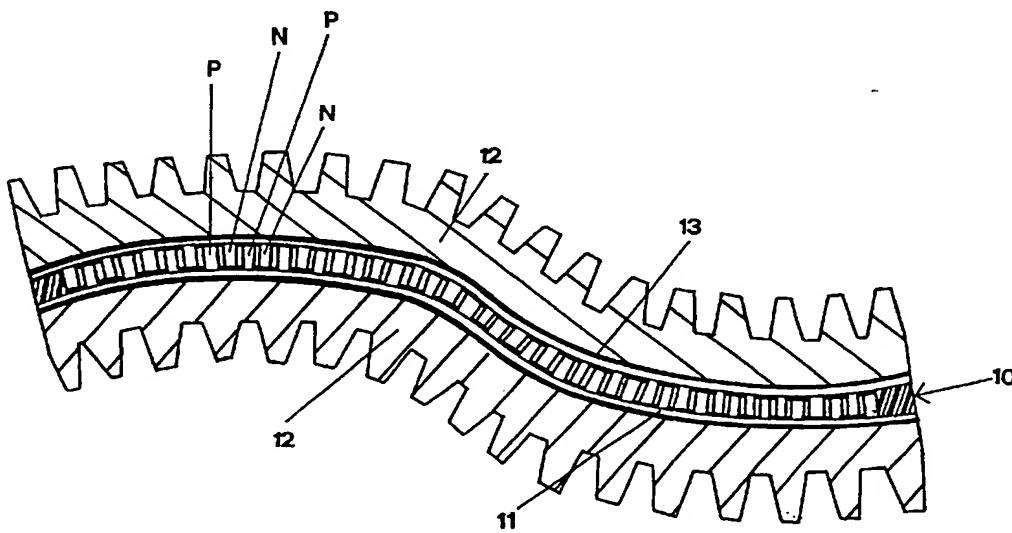
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(54) Title: INTEGRATED THERMOELECTRIC MODULE



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Abstract: The integrated thermoelectric module is formed of a set of thermoelectric elements, consisting of N type and P type semiconductor and/or semiconductor elements electrically connected in series and/or in parallel and thermally connected in parallel and being assembled on flexible supports (11) of polymeric material, capable of electrically isolating said circuit, but having a high thermal conductivity efficiency. Each support (11) is connected to a heat exchanger (12) by means of connection materials (13) having low thermal impedance allowing optimum connection even at low adhesion pressures. The thermoelectric elements are distributed in its interior part so as to geometrically harmonize heat transferred from the integrated thermoelectric module with heat exchanged by the heat exchangers, thus making the temperature distribution on said exchangers as uniform as possible.